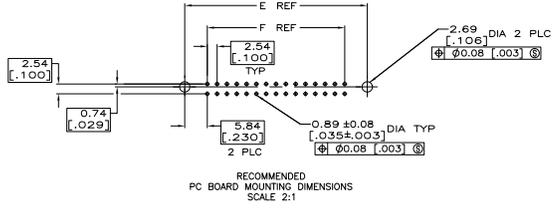
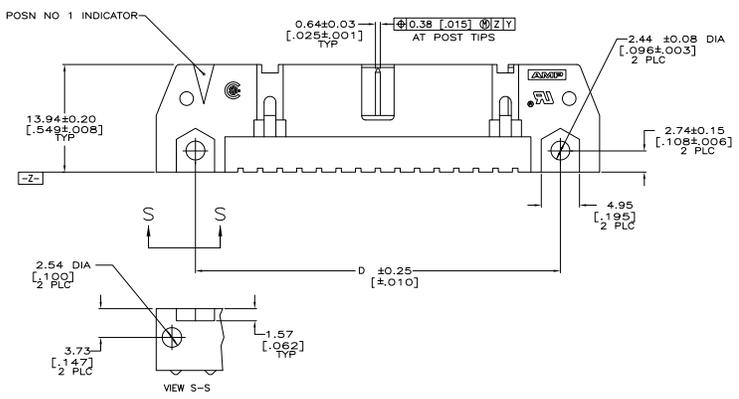
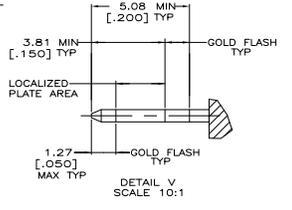
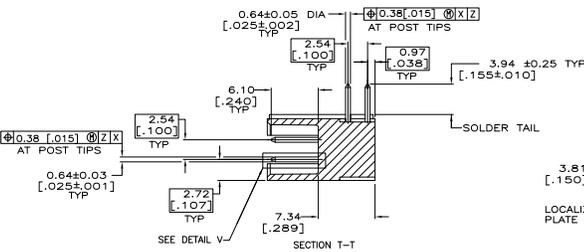
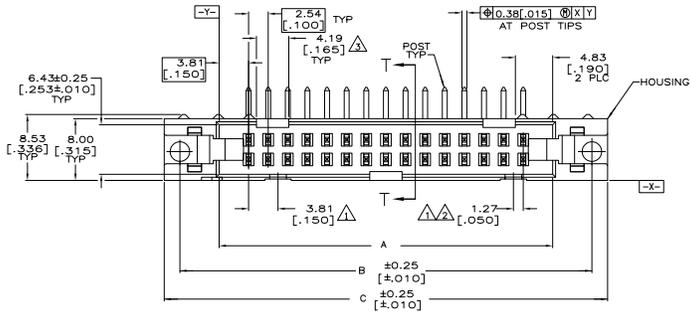


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REV	DATE	DESCRIPTION	BY	APP
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L		REVISED FOR ECO-10-011003	23NOV10	HMR/SB



THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 11-28-05	BY: [Signature]
DRAWN BY: [Signature]		DATE: 11-28-05	BY: [Signature]
CHECKED BY: [Signature]		DATE: 11-28-05	BY: [Signature]
APPROVED BY: [Signature]		DATE: 11-28-05	BY: [Signature]
PROJECT NAME: 108-40018		DATE: 11-28-05	BY: [Signature]
CUSTOMER DRAWING: [Signature]		DATE: 11-28-05	BY: [Signature]
DRAWING NO: 108-40018		DATE: 11-28-05	BY: [Signature]
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REV: 20		DATE: 11-28-05	BY: [Signature]

REV	DATE	DESCRIPTION	BY	CHK	APP
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- △ COORDINATE DIMENSION APPLIES FROM BASIC LOCATION.
- △ 10 AND 14 POSITION SIZES CONTAIN ONLY ONE SLOT FOR SNAP-IN POLARIZER (MILITARY POLARIZATION) LOCATED AS SHOWN.
- △ 10 POSITION SIZES CONTAIN ONLY ONE SLOT FOR DUAL POLARIZATION, LOCATED AS SHOWN.
- 4. RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS IS 3.18 [125].
- △ POSTS:
 GOLD FLASH OVER PALLADIUM-NICKEL PLATE, 0.38µm [.000015] MIN TOTAL ON THE LOCALIZED PLATE AREA.
 2.54µm [.000100] MIN TIN-LEAD PLATE ON THE SOLDER-TAIL.
 1.27µm [.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE POST.
 OR
 0.38µm [.000015] MIN GOLD PLATE ON THE LOCALIZED PLATE AREA.
 2.54µm [.000100] MIN TIN-LEAD PLATE ON THE SOLDER-TAIL.
 1.27µm [.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE POST.
- △ MATERIAL:
 HOUSING: GLASS FILLED NYLON OR POLYESTER, 94V-0 RATED, BLACK.
 POSTS: BRASS.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER DRENAUD/D.SINISI

	F	E	D	C	B	A	NO OF POSN	PART NUMBER
OBSOLETE	53.34	65.02	65.02	75.18	71.12	60.96	44	1-102161-3
	2.100	2.560	2.560	2.960	2.800	2.400		
OBSOLETE	78.74	90.42	90.42	100.58	96.52	86.36	64	1-102161-2
	3.100	3.560	3.560	3.960	3.800	3.400		
OBSOLETE	73.66	85.34	85.34	95.50	91.44	81.28	60	1-102161-1
	2.900	3.360	3.360	3.760	3.600	3.200		
OBSOLETE	60.96	72.64	72.64	82.80	78.74	68.58	50	1-102161-0
	2.400	2.860	2.860	3.260	3.100	2.700		
OBSOLETE	48.26	59.94	59.94	70.10	66.04	55.88	40	102161-9
	1.900	2.360	2.360	2.760	2.600	2.200		
	40.64	52.32	52.32	62.48	58.42	48.26	34	102161-8
	1.600	2.060	2.060	2.460	2.300	1.900		
△ SUPERCEDED	35.56	47.24	47.24	57.40	53.34	43.18	30	102161-7
	1.400	1.860	1.860	2.260	2.100	1.700		
OBSOLETE	30.48	42.16	42.16	52.32	48.26	38.10	26	102161-6
	1.200	1.660	1.660	2.060	1.900	1.500		
	27.94	39.62	39.62	49.78	45.72	35.56	24	102161-5
	1.100	1.560	1.560	1.960	1.800	1.400		
	22.86	34.54	34.54	44.70	40.64	30.48	20	102161-4
	0.900	1.360	1.360	1.760	1.600	1.200		
OBSOLETE	17.78	29.46	29.46	39.62	35.56	25.40	16	102161-3
	0.700	1.160	1.160	1.560	1.400	1.000		
	15.24	26.92	26.92	37.08	33.02	22.86	14	102161-2
	0.600	1.060	1.060	1.460	1.300	0.900		
OBSOLETE	10.16	21.84	21.84	32.00	27.94	17.78	10	102161-1
	0.400	0.860	0.860	1.260	1.100	0.700		

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INCHES	UNLESS OTHERWISE SPECIFIED	PROJECT FILE	108-40018	HEADER ASSY, UNIVERSAL AMP-LATCH	
FRAC	DECIMALS	REV. 00	DATE 11-28-08	DRAWING NO. 102161	
DEC	THOUSANDS	REV. 00	DATE 11-28-08	CUSTOMER DRAWING	
THOUSANDS	HUNDREDS	REV. 00	DATE 11-28-08	PAGE 2 OF 2	